



Material Content Data Sheet



Sales Product Name	ESD5V3S1B-02LS E6327			Issued		29. August 2013		
MA#	MA000879176							
Package	PG-TSSLP-2-1			Weight*		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2320	
	noble metal	gold	7440-57-5	0.001	0.90		8988	
	inorganic material	silicon	7440-21-3	0.017	10.97	12.10	109725	121033
leadframe	non noble metal	nickel	7440-02-0	0.036	24.18	24.18	241752	241752
wire	noble metal	gold	7440-57-5	0.003	1.89	1.89	18886	18886
encapsulation	organic material	carbon black	1333-86-4	0.001	0.54		5418	
	plastics	epoxy resin	-	0.011	7.31		73110	
	inorganic material	silicondioxide	60676-86-0	0.070	46.31	54.16	463022	541550
leadfinish	noble metal	gold	7440-57-5	0.004	2.73	2.73	27341	27341
plating	noble metal	silver	7440-22-4	0.007	4.94	4.94	49438	49438
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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